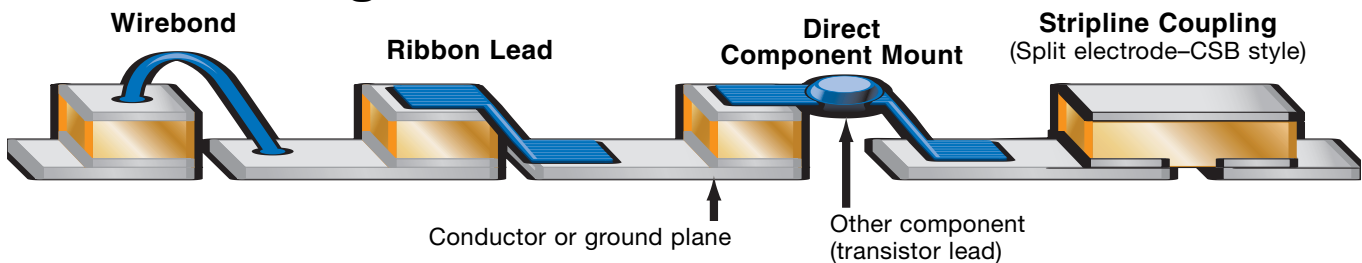


Assembly and Packaging

COMPEX recognizes the importance of maintaining dimensional consistency from lot to lot for any given part at any point in time. We, therefore, place size limits on minimum and maximum length, width and thickness. This is especially important for automatic component placement, chip-on-chip, multiple bonds, micro stripline matching, and cavity insertion.

- WE GUARANTEE THAT HAVING ONCE CHOSEN THE PROPER CHIP SIZE FOR YOUR APPLICATION, THERE WILL BE NO DIMENSIONAL CHANGES BEYOND PERMISSIBLE TOLERANCES AT ANY TIME.

Common Configurations



Common Mounting Methods

- Soldering with the use of pre-tinning and solder reflow, solder preforms, solder paste, etc.
- Eutectic bonding with appropriate metallizations of the surfaces to be joined and the use of compatible interface preforms.
- Conductive Epoxy

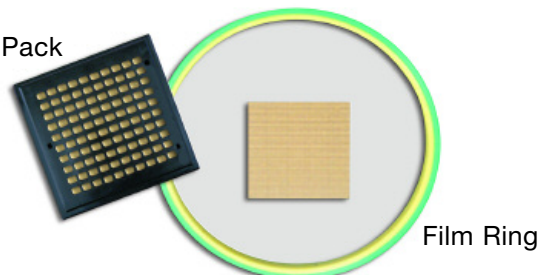
Common Termination Methods

- Soldering of wire or ribbon leads (minimum chip size limited by user's soldering techniques).
- Thermal compression, thermasonic, or ultrasonic bonding with aluminum or gold wire.

Packaging Options

Waffle packs are standard, although film rings, Gel-Paks, Surf-Tape and bulk packaging are also available upon request.

Waffle Pack



Film Ring